

FORM PTO-1449(Modified)

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S  
INFORMATION DISCLOSURE STATEMENT

ATTY. DOCKET NO. H0498.70114US01

SERIAL NO. 10/677,103

APPLICANT Enoch Kim et al.

FILING DATE 10/01/2003

GROUP ART UNIT: 1732

## U.S. PATENT DOCUMENTS

Exam Init	Ref Des	Document No.	Date	Name	Class	Sub Class	FILING DATE If Appropriate
MOV	*	3,873,359	03/25/75	Lando			
A	*	3,873,360	03/25/75	Lando	1		
	*	3,900,614	08/19/75	Lando			
	*	4,098,922	07/04/78	Dinella et al.			
	*	4,100,037	07/11/78	Baron et al.			
	*	4,192,764	07/11/80	Madsen			
	*	4,258,001	03/24/81	Pierce et al.			
	*	4,322,457	03/30/82	Baron et al.			
	*	4,472,458	09/18/84	Sirinyan et al.			
	*	4,508,755	04/02/85	Reintjes et al.			
	*	4,555,414	11/26/85	Hoover et al.			
	*	4,637,904	01/87	Rounds			
	*	4,690,715	09/01/87	Allara et al.			
	*	4,710,401	12/87	Warren Jr. et al.			
	*	4,728,591	03/01/88	Clark et al.			
	*	4,802,951	02/07/89	Clark et al.			
	*	4,869,778	09/89	Cote			
	*	4,959,252	09/25/90	Bonnebat et al.			
	*	5,073,495	12/17/91	Anderson			
	*	5,079,600	01/07/92	Schnur et al.			
	*	5,087,510	02/11/92	Tokas et al.			
	*	5,141,785	08/25/92	Yoshinada et al.			
	*	5,170,461	12/08/92	Yoon et al.			
	*	5,227,474	07/13/93	Johnson			
	*	5,259,926	11/09/93	Kuwabara et al.			
	*	5,345,869	09/13/94	Treverton et al.			
	*	5,385,116	01/31/95	Hattori et al.			
	*	5,439,829	08/08/95	Anderson et al.			
	*	5,471,455	11/28/95	Jabr			
	*	5,484,324	01/16/96	Okabayashi et al.			
	*	5,512,131	04/30/96	Kumar et al.			
	*	5,534,101	07/09/96	Keyworth et al.			
	*	5,620,850	04/15/97	Bamdad et al.			
MOV	*	5,976,826	11/02/99	Singhvi et al.			

\* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. \_\_\_\_\_, filed \_\_\_\_\_, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

Examiner

*M. Vengat*

DATE CONSIDERED

*12/22/06*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.

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JUN 04 2004

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APPLICANTS: Enoch Kim et al.

FILING DATE 10/01/2003

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## U.S. PATENT DOCUMENTS

Exam Init	Ref Des	Document No.	Date	Name	Class	Sub Class	FILING DATE If Appropriate
MDV	*	5,989,835	11/23/99	Dunlay et al.			
↑	*	6,103,479	08/15/00	Taylor			
↓		6,355,198	03/12/02	Kim et al.			
↓		6,660,192	12/09/03	Kim et al.			
MDV		2002-0066978	06/06/02	Kim et al.			

## FOREIGN PATENT DOCUMENTS

		Country & Doc. No. (11)	Pub. Date (43)		Class	Sub Class	Translation Yes No
MDV	*	EP 0112721	07/04/84	Comtech Research Unit Limited			
↑	*	EP 0672765 A1	09/20/95	Studiengesellschaft Kohle mbH			
↓	*	JP 07237229	02/25/94	Canon Inc.			
↓	*	JP 2165933	06/26/90	Motoyuki			
↓	*	WO 96/29629	09/26/96	Whitesides et al.			
↓	*	WO 97/07429	02/27/97	Clem et al.			
MDV	*	WO 97/33737	09/18/97	Enoch Kim et al.			

## OTHER ART

(Including Author, Title, Date, Pertinent Pages, Publication, Etc.)

MDV	*	P.M. St. John et al., "Microcontact printing and pattern transfer using trichlorosilanes on oxide substrates," <i>Appl. Phys. Lett.</i> , Vol. 68, No. 7, pp. 1022-24, February 12, 1996.
↑	*	E. Kim et al., "Two-and Three-Dimensional Crystallization of Polymeric Microspheres by Micromolding in Capillaries," <i>Advanced Materials</i> , Vol. 8, No. 3, pp. 245-47, March 1, 1996.
↓	*	E. Kim et al., "Combining Patterned Self-Assembled Monolayers of Alkanethiolates on Gold with Anisotropic Etching of Silicon to Generate Controlled Surface Morphologies," <i>J. Electrochem. Soc.</i> , Vol. 142, No. 2, pp. 628-33, February 1995.
↓	*	T.P. Moffat et al., "Patterned Metal Electrodeposition Using an Alkanethiolate Mask," <i>J. Electrochem. Soc.</i> , Vol. 142, No. 11, November 1995.
↓	*	E.A. Dobisz et al., "Self-Assembled Monolayer Films for Nanofabrication," <i>Mat. Res. Soc. Symp. Proc.</i> , Vol. 380, 1995.
↓	*	J.K. Schoer et al., "Scanning Probe Lithography," <i>Langmuir</i> , Vol. 10, No. 3, pp. 617-18, 1994.
↓	*	H.C. Haverkorn van Rijsewijk, et al., "Manufacture of LaserVision video discs by a photopolymerization process," <i>Philips Technical Review</i> , Vol. 40, No. 10 (1982), pp. 287-97.
↓	*	M. Emmelius et al., "Materials for Optical Data Storage," <i>Ignew. Chem. Int. Ed. Engl.</i> 28, Vol. 28, No. 11, (1989), pp. 1445-1600.
↓	*	F. Lenzman et al., "Thin-Film Micropatterning Using Polymer Microspheres," <i>Chem. Mater.</i> , Vol. 6, (1994), pp. 156-59.
↓	*	S. Chou et al., "Imprint of sub-25 nm vias and trenches in polymers," <i>Appl. Phys. Lett.</i> 67 (21), 1995, pp. 3114-6.
↓	*	C.D. Dushkin et al., "Colored Multilayers from Transparent Submicrometer Spheres," <i>Langmuir</i> , Vol. 9 (1993), pp. 3695-3701.
MDV	*	S. Hayashi et al., "Imaging by Polystyrene Latex Particles," <i>Journal of Colloid &amp; Interface Science</i> , Vol. 144, No. 2 (1991), pp. 538-47.

\* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. \_\_\_\_\_, filed \_\_\_\_\_, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

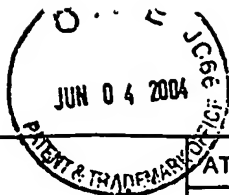
Examiner

M. Vargot

DATE CONSIDERED

12/22/06

EXAMINER: Initial reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.



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APPLICANTS: Enoch Kim et al.

FILING DATE 10/01/2003

GROUP ART UNIT: 1732

## OTHER ART

(Including Author, Title, Date, Pertinent Pages, Publication, Etc.)

NOV	*	Y. Xia et al., "Microcontact Printing of Octadecylsiloxane on the Surface of Silicon Dioxide and its Application in Microfabrication," <i>J. Am. Chem. Soc.</i> , Vol. 117, No. 37 (1995), pp. 9576-9577.
	*	J.F. Dijkstra, "Analysis of the injection-molding process," <i>Philips Tech. Rev.</i> 44, No. 7, (1989), pp. 212-217.
	*	J. Shaw, "Capillary fill encapsulation of ISFETs," <i>Sensors and Actuators A</i> , 37-38, (1993), pp. 74-76.
	*	J. Jacobs et al., "Combinatorial chemistry - applications of light-directed chemical synthesis," <i>Tibtech</i> , Vol. 12 (1994), pp. 19-26.
	*	S. Sundberg et al., "Spatially-Addressable Immobilization of Macromolecules on Solid Supports," <i>J. Am. Chem. Soc.</i> , Vol. 117 (1995), pp. 12050-12057.
	*	C. Gorman et al., "Fabrication of Patterned, Electrically Conducting Polypyrrole Using a Self-Assembled Monolayer: A Route to All-Organic Circuits," <i>Chem. Mater.</i> 7, (1995), pp. 526-629.
	*	J. Wilbur et al., "Microfabrication by Microcontact Printing of Self-Assembled Monolayers," <i>Adv. Mater.</i> 6, No. 7/8, (1994), pp. 600-04.
	*	E. Kim et al., "Polymer microstructures formed by moulding in capillaries," <i>Nature</i> , Vol. 376, (1995) pp. 581-84.
	*	A. Kumar et al., "Patterning Self-Assembled Monolayers: Applications in Material Science," <i>Langmuir</i> , 10, (1994) pp. 1498-1511.
	*	D. Pritchard et al., "Micron-Scale Patterning of Biological Molecules," <i>Angew. Chem. Int. Ed. Engl.</i> 34, No. 1 (1995), pp. 91-3.
	*	S. Potochnik et al., "Selective Copper Chemical Vapor Deposition Using Pd-Activated Organosilane Films," <i>Langmuir</i> , Vol. 11, No. 6, (1995), pp. 1841-1845.
	*	W. Dressick et al., "Patterning of Self-Assembled Films Using Lithographic Exposure Tools," <i>Jpn. J. Appl. Phys.</i> , Vol. 32 (1993), pp. 5829-5839.
	*	G. Lazarov et al., "Formation of Two-dimensional Structures from Colloidal Particles on Fluorinated Oil Substrate," <i>J. Chem. Soc. Faraday Trans. 90</i> (14), (1994), pp. 2077-2083.
	*	P. Hoyer et al., "Small quantum-sized CdS particles assembled to form a regularly nanostructured porous film," <i>Appl. Phys. Lett.</i> 66 (20) (1995), pp. 2700-02.
	*	H. Bonnemenn et al., "Preparation and Catalytic Properties of NR+4-Stabilized Palladium Colloids," <i>Applied Organometallic Chemistry</i> , Vol. 8 (1994), pp. 361-378.
	*	K. Nagayami, "Fabrication of Two-Dimensional Colloidal Arrays," <i>Phase Transitions</i> , Vol. 45, (1993), pp. 185-203.
	*	M. Reetz et al., "Size-Selective Synthesis of Nanostructured Transition Metal Clusters," <i>J. Am. Chem. Soc.</i> 116 (1994), pp. 7401-7402.
	*	M. Reetz et al., "Visualization of Surfactants on Nanostructured Palladium Clusters by a Combination of STM and High-Resolution TEM," <i>Science</i> , Vol. 267 (1995), pp. 367-369.
	*	F. Meldrum et al., "Formation of Thin Films of Platinum, Palladium, and Mixed Platinum: Palladium Nano-crystallites by the Langmuir Monolayer Technique," <i>Chem. Mater.</i> 7 (1995), pp. 1112-1116.
NOV	*	T. Vargo et al., "Adhesive Electroless Metallization of Fluoropolymeric Substrates," <i>Science</i> , Vol. 262 (1993), pp. 1711-1712.

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Examiner

*M. Vargo*

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*12/22/06*

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MOV	*	J. Calvert et al., "Deep ultraviolet patterning of monolayer films for high resolution lithography," <i>J. Vac. Sci. Technol. B9</i> (6) (1991), pp. 3447-3450.
A	*	J. Li et al., "Copper-Based Metallization for ULSI Applications," <i>MRS Bulletin</i> , (1993), pp. 18-21.
	*	J. Chou et al., "Electroless Cu for VLSI", <i>MRS Bulletin</i> (1993), pp. 31-37.
	*	A. van der Putten et al., "Electrochemistry of Colloidal Palladium," <i>J. Electrochem. Soc.</i> , Vol. 139, No. 12 (1992) pp. 3475-3480.
	*	C. Ting et al., "Selective Electroless Metal Deposition of Integrated Circuit Fabrication," <i>J. Electrochem. Soc.</i> , Vol. 136, No. 2, (1989), pp. 456-462.
	*	R. Jackson, "Pd+2/Poly(acrylic acid) Thin Films as Catalysts for Electroless Copper Deposition: Mechanism of Catalyst Formation," <i>J. Electrochem. Soc.</i> , Vol. 137, No. 1, (1990), pp. 95-101.
	*	A. van der Putten et al., "Anisotropic Deposition of Electroless Nickel," <i>J. Electrochem. Soc.</i> , Vol. 140, No. 8 (1993), pp. 2229-2235.
	*	A. van der Putten, "Controlled Mechanical Adhesion of Electroless Cu Patterns," <i>J. Electrochem. Soc.</i> , Vol. 140 No. 8, (1993), pp. 2376-2378.
	*	R. Jackson, "Initiation of Electroless Copper Plating Using Pd+2/Poly(acrylic acid) Films," <i>J. Electrochem. Soc.</i> (1998), pp. 3172-3173.
	*	C. Mak, "Electroless Copper Deposition on Metals and Metal Silicides," <i>MRS Bulletin</i> , (1994), pp. 55-62.
	*	W. Dressick et al., "Photopatterning and Selective Electroless Metallization of Surface-Attached Ligands," <i>J. Chem. Mater.</i> 5, (1993), pp. 148-150.
	*	S. Nakahara et al., "Microstructure and Mechanical Properties of Electroless Copper Deposits," <i>Annu. Rev. Mater. Sci.</i> 21, (1991), pp. 93-129.
	*	N. Jeon et al., "Patterned Self-Assembled Monolayers Formed by Microcontact Printing Direct Selective Metalization by Chemical Vapor Deposition on Planar and Nonplanar Substrates," <i>Langmuir</i> 11 (1995), pp. 3204-3206.
MOV	*	V. Dubin, "Electroless Ni-P Deposition on Silicon with Pd Activation," <i>J. Electrochem. Soc.</i> , Vol. 139, No. 5, May, 1992, pps. 1289-1294.

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Examiner

*M. Vargut*

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FORM PTO-1449 (modified PTO/SB/08)

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

APPLICATION NO.: 10/677103

ATTY. DOCKET NO.: H0498.70114US01

FILING DATE: October 1, 2003

CONFIRMATION NO.: 4302

APPLICANT: Enoch Kim et al.

GROUP ART UNIT: 1732

EXAMINER: Not Yet Assigned

Sheet 1 of 1

**U.S. PATENT DOCUMENTS**

Examiner's Initials #	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication or Issue of Cited Document MM-DD-YYYY
		Number	Kind Code		
MDV		6,766,817	V2	da Silva	07-27-2004

**FOREIGN PATENT DOCUMENTS**

Examiner's Initials #	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Translation (Y/N)
		Office/ Country	Number	Kind Code			

**OTHER ART — NON PATENT LITERATURE DOCUMENTS**

Examiner's Initials #	Cite No	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	Translation (Y/N)

EXAMINER: <i>M. Vagot</i>	DATE CONSIDERED: <i>12/22/06</i>
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